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Packaging of components for automatic handling – Part 5: Matrix trays

INTERNATIONAL
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COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 5: Matrix trays

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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This Redline version provides you with a quick and easy way to compare all the changes between this standard and its previous edition. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in strikethrough red text.

International Standard IEC 60286-5 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 2003 and Amendment 1:2009. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) The generic rules for the design of matrix trays are given in this document. Newly developed trays which follow these rules will not be listed individually. Only those trays which conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.
b) An update of the matrix trays, which do not conform to the design rules set forth herein, are considered as "non-standard trays" and are not preferred for use, is listed in Annex A.

The text of this International Standard is based on the following documents:

CDV	Report on voting
40/2556/CDV	40/2597/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60286 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 5: Matrix trays

1 Scope

This part of IEC 60286 describes the common dimensions, tolerances and characteristics of the tray. It includes only those dimensions that are essential for the handling of the trays for the stated purpose and for placing or removing components from the trays.

Matrix trays are designed to facilitate the transport and handling of electronic components during their testing, baking, transport/storage, and final mounting by automatic placement equipment.

The generic rules for their design are given in this document. Newly developed trays that follow these rules will not be listed individually. Only those trays that conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.

NOTE Matrix trays listed in Annex A that do not conform to the design rules set forth herein shall be considered as "non-standard trays" and are not preferred for use.

2 Normative references

There are no normative references in this document.

IEC 60286-5

Edition 3.0 2018-04

INTERNATIONAL STANDARD

Packaging of components for automatic handling – Part 5: Matrix trays



IEC 60286-5:2018-04(en)

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A bilingual version of this publication may be issued at a later date.

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